

# Description

The KGF65A6H and MGF65A6H are 650 V Field Stop IGBTs. Sanken original trench structure decreases gate capacitance, and achieves high speed switching and switching loss reduction. Thus, these Field Stop IGBTs can improve the efficiency of your circuit.

## **Features**

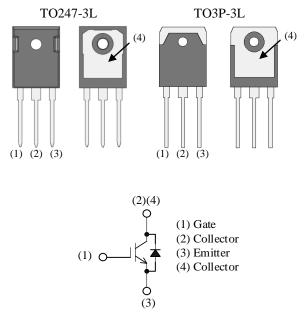
- Low Saturation Voltage
- High Speed Switching
- With Integrated Fast Recovery Diode
- RoHS Compliant

- V<sub>CE</sub> ------ 650 V
  I<sub>C</sub> (T<sub>C</sub> = 100 °C) ------ 60 A
  Short Circuit Withstand Time ----- 10 μs

# **Applications**

- Welding Invertor
- PFC Circuit





Not to scale

## **Selection Guide**

Part Number	Package
KGF65A6H	TO247-3L
MGF65A6H	TO3P-3L

# **Absolute Maximum Ratings**

Unless otherwise specified,  $T_A = 25$  °C.

Parameter	Symbol	Conditions	Rating	Unit	Remarks
Collector to Emitter Voltage	V <sub>CE</sub>		650	V	
Gate to Emitter Voltage	$V_{GE}$		±30	V	
Continuous Collector Current <sup>(1)</sup>	т	$T_C = 25 \ ^{\circ}C$	80 <sup>(2)</sup>	А	
	I <sub>C</sub>	$T_{C} = 100 \ ^{\circ}C$	60	А	
Pulsed Collector Current	I <sub>C(PULSE)</sub>	$PW \le 1 ms,$ duty cycle $\le 1\%$	180	А	
Diode Continuous Forward Current <sup>(1)</sup>	$\mathrm{I_{F}}$	$T_C = 25 \ ^{\circ}C$	40 <sup>(2)</sup>	А	
Diode Continuous Forward Current		$T_{C} = 100 \ ^{\circ}C$	30	А	
Diode Pulsed Forward Current	I <sub>F(PULSE)</sub>	$PW \le 1 \text{ ms},$ duty cycle $\le 1\%$	100	А	
Short Circuit Withstand Time	t <sub>SC</sub>	$V_{GE} = 15 \text{ V}, \\ V_{CE} = 400 \text{ V}, \\ T_J = 175 \text{ °C}$	10	μs	
Power Dissipation	P <sub>D</sub>	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$	405	W	
Operating Junction Temperature	T <sub>J</sub>		175	°C	
Storage Temperature	T <sub>STG</sub>		-55 to 150	°C	

## **Thermal Characteristics**

Unless otherwise specified,  $T_A = 25$  °C.

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	Remarks
Thermal Resistance of IGBT (Junction to Case)	$R_{\theta JC}$ (IGBT)			—	0.38	°C/W	
Thermal Resistance of Diode (Junction to Case)	$R_{\theta JC}(Di)$			_	1.15	°C/W	

<sup>&</sup>lt;sup>(1)</sup>  $I_C$  and  $I_F$  are determined by the maximum junction temperature for TO3P-3L package. <sup>(2)</sup> Determined by bonding wires capability.

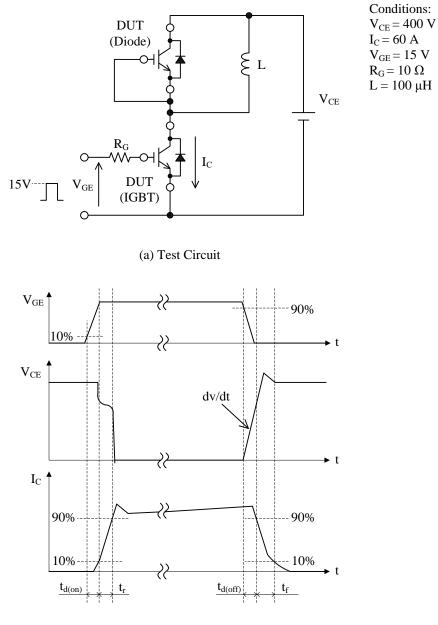
# **Electrical Characteristics**

Unless otherwise specified,  $T_A = 25$  °C.

Parameter Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Collector to Emitter Breakdown Voltage	V <sub>(BR)CES</sub>	$I_{\rm C} = 100 \ \mu A, V_{\rm GE} = 0 \ V$	650			V	
Collector to Emitter Leakage Current	I <sub>CES</sub>	$V_{CE} = 650 \text{ V}, V_{GE} = 0 \text{ V}$	—		100	μΑ	
Gate to Emitter Leakage Current	I <sub>GES</sub>	$V_{GE} = \pm 30 \text{ V}$			±500	nA	
Gate Threshold Voltage	V <sub>GE(TH)</sub>	$V_{CE} = 10 \text{ V}, I_C = 1 \text{ mA}$	4.0	5.5	7.0	V	
Collector to Emitter Saturation Voltage	V <sub>CE(sat)</sub>	$V_{GE} = 15 \text{ V}, I_C = 60 \text{ A}$		1.9	2.37	V	
Input Capacitance	C <sub>ies</sub>	$V_{CE} = 20 V,$		3500			
Output Capacitance	C <sub>oes</sub>	$V_{GE} = 0 V,$	—	330	—	pF	
Reverse Transfer Capacitance	C <sub>res</sub>	f = 1.0 MHz		170	—		
Gate Charge	$Q_{g}$	$V_{CE} = 520 \text{ V}, I_C = 60 \text{ A},$ $V_{GE} = 15 \text{ V}$		110		nC	
Turn-On Delay Time	t <sub>d(on)</sub>			50		ns	
Rise Time	t <sub>r</sub>			70	—		
Turn-Off Delay Time	$t_{d(off)}$	$T_{J} = 25 ^{\circ}C;$	_	130	_		
Fall Time	t <sub>f</sub>	see Figure 1		40			
Turn-on Energy <sup>(3)</sup>	Eon			1.4		. T	
Turn-off Energy	E <sub>off</sub>		_	1.3	_	mJ	
Turn-On Delay Time	t <sub>d(on)</sub>			50			
Rise Time	t <sub>r</sub>			70			
Turn-Off Delay Time	$t_{d(off)}$	$T_{I} = 175 \ ^{\circ}C;$		160		ns	
Fall Time	t <sub>f</sub>	see Figure 1		60			
Turn-on Energy <sup>(3)</sup>	Eon	1		2.1		. T	
Turn-off Energy	E <sub>off</sub>	1		1.8		mJ	
Emitter to Collector Diode Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 30 A		1.8		V	
Emitter to Collector Diode Reverse Recovery Time	t <sub>rr</sub>	$ I_F = 30 \text{ A}, \\ di/dt = 700 \text{ A}/\mu s $		50		ns	

<sup>&</sup>lt;sup>(3)</sup> Energy losses include the reverse recovery of diode.

# **Test Circuits and Waveforms**



(b) Waveform

Figure 1. Test Circuits and Waveforms of dv/dt and Switching Time

#### **Rating and Characteristic Curves**

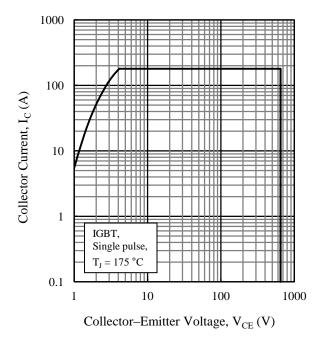


Figure 2. IGBT Reverse Bias Safe Operating Area

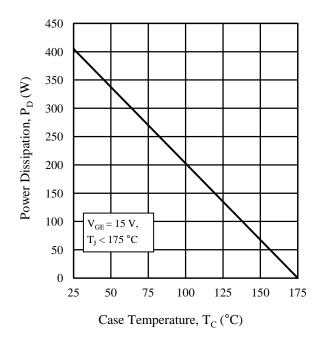


Figure 4. Power Dissipation vs. Case Temperature

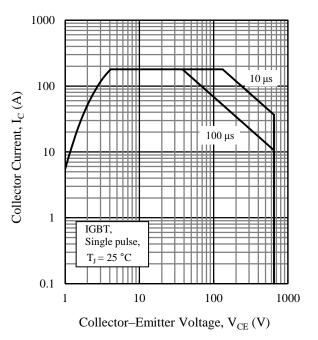


Figure 3. IGBT Safe Operating Area

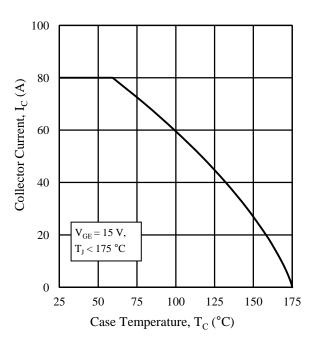


Figure 5. Collector Current vs. Case Temperature

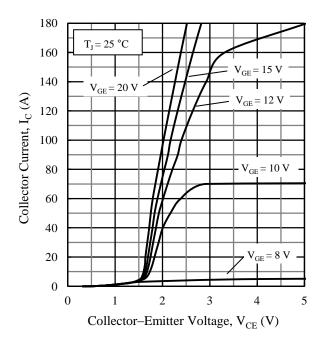


Figure 6. Output Characteristics ( $T_J = 25 \ ^{\circ}C$ )

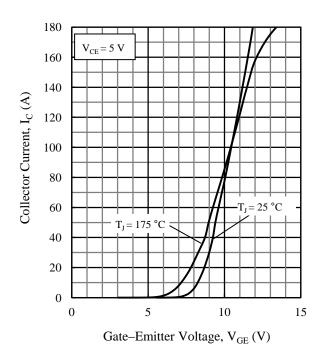


Figure 8. Transfer Characteristics

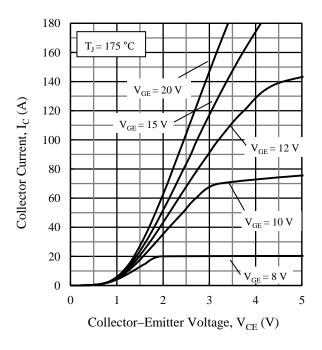


Figure 7. Output Characteristics ( $T_J = 175 \ ^{\circ}C$ )

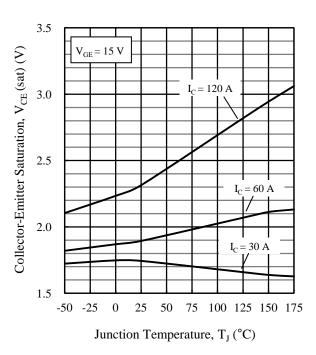


Figure 9. Saturation Voltage vs. Junction Temperature

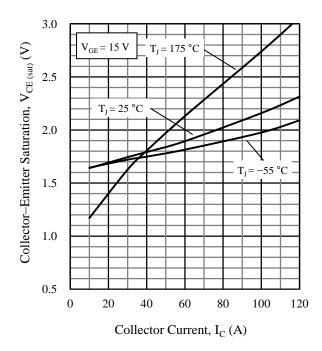


Figure 10. Saturation Voltage vs. Collector Current

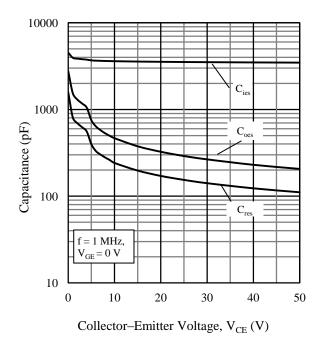


Figure 12. Capacitance Characteristics

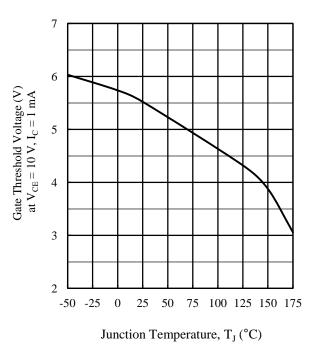


Figure 11. Gate Threshold Voltage vs. Junction Temperature

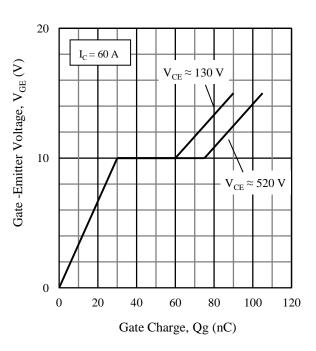


Figure 13. Typical Gate Charge

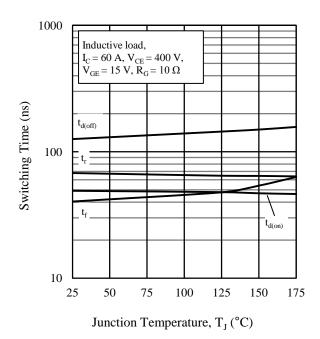


Figure 14. Switching Time vs. Junction Temperature

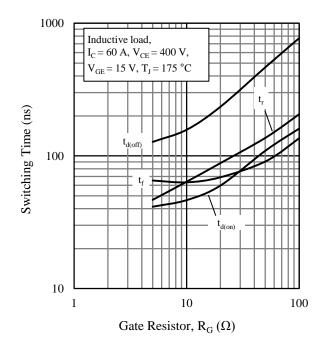


Figure 16. Switching Time vs. Gate Resistor

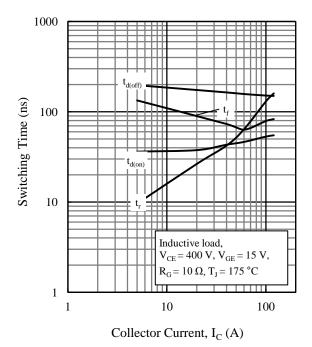


Figure 15. Switching Time vs. Collector Current

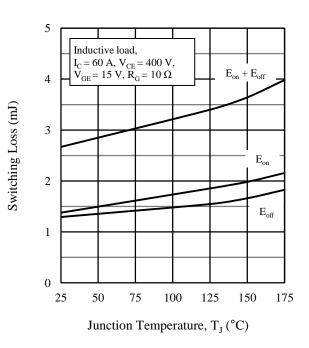


Figure 17. Switching Loss vs. Junction Temperature

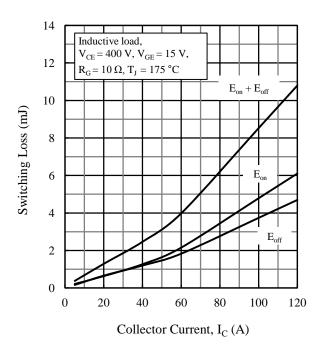
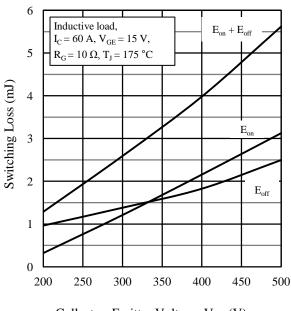


Figure 18. Switching Loss vs. Collector Current



Collector–Emitter Voltage,  $V_{CE}(V)$ 

Figure 20. Switching Loss vs. Collector–Emitter Voltage

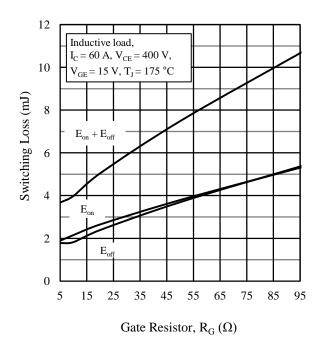


Figure 19. Switching Loss vs. Gate Resistor

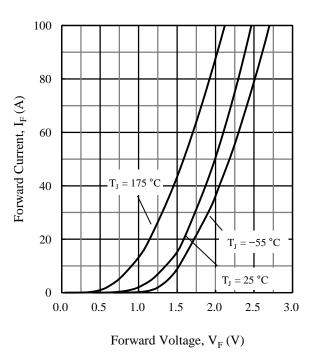
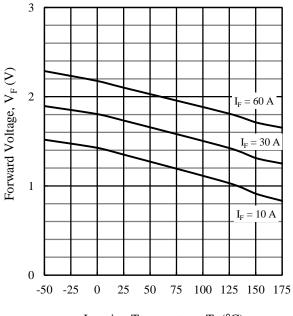


Figure 21. Diode Forward Characteristics



Junction Temperature,  $T_J$  (°C)

Figure 22. Diode Forward Voltage vs. Junction Temperature

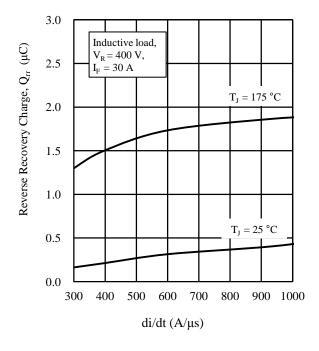


Figure 24. Diode Reverse Recovery Charge vs. di/dt

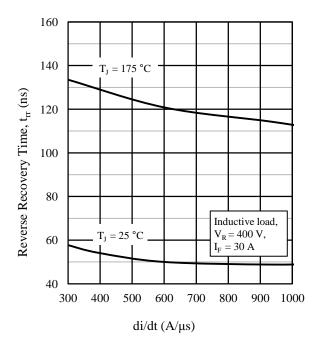


Figure 23. Diode Reverse Recovery Time vs. di/dt

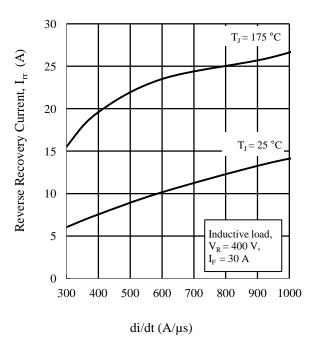


Figure 25. Diode Reverse Recovery Current vs. di/dt

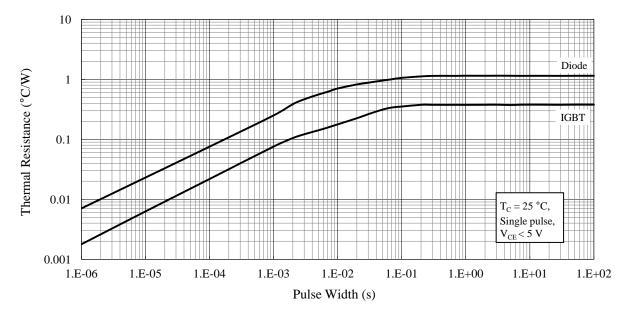
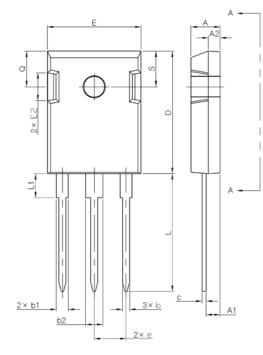


Figure 26. Transient Thermal Resistance

# **Physical Dimensions**

#### • TO247-3L



(A-A)	
ØP	
	DI

SYMBOL	MIN	NOM	MAX	
A	4.83	5.02	5.21	
A1	2.29	2.41	2.54	
A2	1.91	2.04	2.16	
b	1.14	1.27	1.40	
b1	1.91	2.10	2.20	
b2	2.92	3.10	3.20	
С	0.61	0.71	0.80	
D	20.80	21.07	21.34	
D1	17.43	17.63	17.83	
E	15.75	15.94	16.13	
E1	13.06	13.26	13.46	
E2	4.32	4.58	4.83	
е	5.25	5.45	5.65	
L	19.81	20.19	20.57	
L1	3.81	4.07	4.32	
ØР	3.55	3.60	3.65	
Q	5.59	5.90	6.20	
S	6.15 BSC			

NOTE

1. THESE DIMENSION DO NOT INCLUDE MOLD PROTRUSION

MAX

5.00

1.65

1.60 1.20

2.20

3.20

0.75

20.10

15.80

5.65

20.20

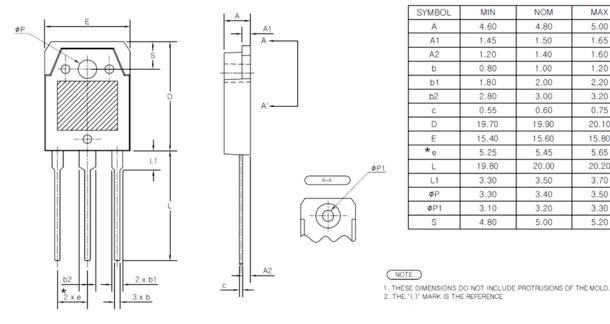
3.70

3.50

3.30

5.20

#### • TO3P-3L



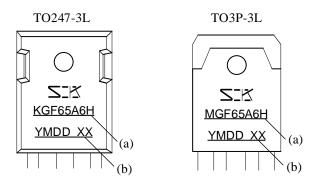
#### NOTES:

- All dimensions in millimeters
- Pin treatment for TO247 and TO3P: Pb-free (RoHS compliant) \_
- When soldering the products, be sure to minimize the working time within the following limits:

 $260 \pm 5$  °C  $10 \pm 1$  s, 2 times (flow)  $380 \pm 10$  °C  $3.5 \pm 0.5$  s, 1 time (soldering iron)

- Soldering should be at a distance of at least 1.5 mm from the body of the products.
- The recommended screw torque for TO247, TO3P and TO3PF: 0.686 N·m to 0.882 N·m (7 kgf·cm to 9 kgf·cm)

# **Marking Diagram**



- (a) Part Number
- (b) Lot Number

Y is the last digit of the year of manufacture (0 to 9) M is the month of the year (1 to 9, O, N, or D) DD is the day of the month (01 to 31)

XX is the control number

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